

# MALS068X

## Silicon planar type

For constant voltage and surge absorption circuits

### ■ Features

- Bi-directional and high electrostatic discharge ESD
- Small terminal capacitance  $C_t$

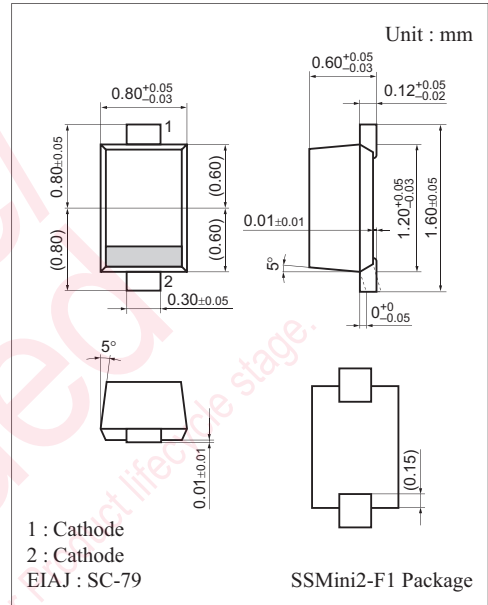
### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Repetitive peak forward current	$I_{FRM}$	200	mA
Total power dissipation *1	$P_T$	150	mW
Junction temperature	$T_j$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$
Electrostatic discharge *2	ESD	$\pm 15$	kV

Note) \*1:  $P_T = 150$  mW achieved with a printed circuit board.

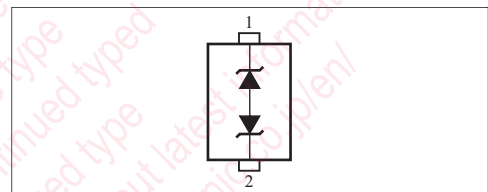
\*2: Test method: IEC61000-4-2

( $C = 150$  pF,  $R = 330 \Omega$ , Contact discharge: 10 times)



Marking Symbol: RX

Internal Connection



### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Zener voltage *	$V_Z$	$I_Z = 5$ mA	6.5	7.0	7.5	V
Zener operating resistance	$R_Z$	$I_Z = 5$ mA			20	$\Omega$
Reverse current	$I_R$	$V_R = 4.0$ V			50	nA
Terminal capacitance	$C_t$	$V_R = 0$ V, $f = 1$ MHz		15		pF

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. The temperature must be controlled  $25^\circ\text{C}$  for  $V_Z$  measurement.

$V_Z$  value measured at other temperature must be adjusted to  $V_Z (25^\circ\text{C})$

3. \*:  $V_Z$  guaranteed 20 ms after current flow.

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